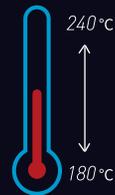


Solder Adhesive

锡胶

低温系列
(Low temperature series)



产品优势 Product advantage



高导电导热性能
锡胶固化后合金锡粉发生冶金连接, 实现高导电导热性能
After solder adhesive cured, alloy is connected with metallurg to achieve high electrical and thermal conductivity;



无锡珠残留, 挥发物少
No solder ball, less volatile



热固胶透明, 表面绝缘电阻高
Transparent hot glue and high SIR



多种焊接固化方式
焊接固化方式可采用回流焊、烤箱等
Soldering curing method can be done by reflow or oven



应用范围广
可应用在: SMT微电子精密元件焊接、半导体与芯片封装、LED固晶封装、FPC产品与镜头模组等领域
Applications: SMT precision component soldering, semiconductor and chip packaging, FPC products & camera module, LED die attach packaging and other fields.

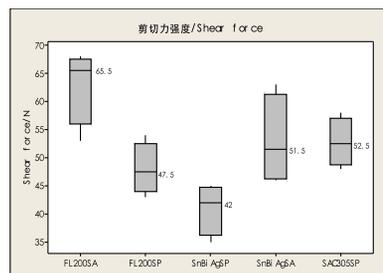
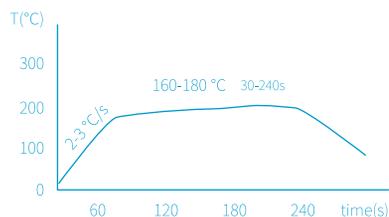
应用 Application

项目 Item	测试条件 Test conditions	
高温高湿 Damp heat	85°C / 85%RH, 168H	
低温储存 Low temp	-30°C, 168H	
高低温冲击测试 TCT	125°C/-40°C, 15min/temp, 100cycles	
交变湿热 Damp heat, cyclic	25°C/95% RH, 55°C/95% RH 1cycle/24h, 3cycles	
跌落测试 Drop	1.5m, 2 times/surface, 6 surface, 140G	1.5m, 2次/面, 共6面 140G
微跌测试 Micro drop	height 10cm, jig 150g, drop surface is steel plate, 10000times/surface, 3 surface	高度10cm, 夹具150g, 跌落底面钢板, 10000次/面, 共3面
滚筒测试 Drum test	height 1m, jig 150g, scrolling speed 10-12times/min, 200 cycle	高度1m, 夹具150g, 滚动速度10-12次/min, 200次循环

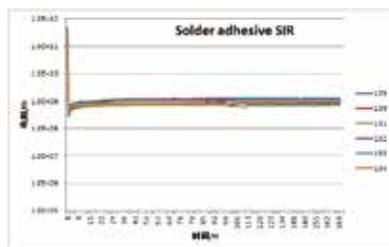
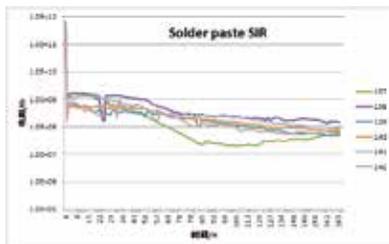


★85°C/85%RH @1000H+85°C/-40°C @1000cycles PASS

炉温曲线图 Furnace temperature curve



表面绝缘电阻 SIR



SAC 系列 (SAC series)

锡胶

Solder Adhesive (SA)



产品优势 Product advantage



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使用工艺 Process



Solder paste



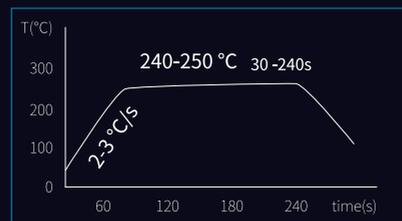
SA



焊点外观 Solder joint appearance



SA炉温曲线图 Furnace temperature curve



自动组装 Self Assembly

